Product Change Notification: JARA-29BSCX099

Date:

05-Oct-2026

Product Category:

Ethernet Phys

Notification Subject:

CCB 8574 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and CRM-1150B as a new die attach material for KSZ8001L, KSZ8001LI, KSZ8001L-TR, KSZ8001LI-TR, KSZ8721BL, KSZ8721BLI, KSZ8721BL-TR, KSZ8721BLI-TR, KSZ8721CL and KSZ8721CL-TR catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package at OSE assembly site.

Affected CPNs:

JARA-29BSCX099_Affected_CPN_10052026.pdf
JARA-29BSCX099_Affected_CPN_10052026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and CRM-1150B as a new die attach material for KSZ8001L, KSZ8001LI, KSZ8001L-TR, KSZ8001LI-TR, KSZ8721BL, KSZ8721BLI, KSZ8721BL-TR, KSZ8721BLI-TR, KSZ8721CL and KSZ8721CL-TR catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package at OSE assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site		Orient Semiconductor Electronics, Ltd (OSE)	Orient Semiconductor Electronics, Ltd (OSE)	No
Wire Material		Au	CuPdAu	Yes
Die Attach Material	Top Die	QMI-550 (PFAS)	CRM-1150B (PFAS-free)	Yes
	Bottom Die	EN4900G	EN4900G	No
Molding Compound Material		CEL-9200HHF	CEL-9200HHF	No
Lead-Frame Material		C7025	C7025	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material and CRM-1150B as a new die attach material at OSE assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: February 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026					>	**February 2027**			
Work Week	40	41	42	43	44		05	06	07	08
Initial PCN Issue Date		X								
Qual Report Availability									X	
Final PCN Issue Date									X	

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 05, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach Explanation.pdf
PCN_JARA-29BSCX099 Qualification Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.